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**Inventor Name Search Result**

Your Search was:

Last Name = FARNWORTH

First Name = WARREN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 50
<u>11108496</u>	Not Issued	020	04/18/2005	GROUP ENCAPSULATED DICING CHUCK	FARNWORTH, WARREN M.
<u>11099066</u>	Not Issued	020	04/05/2005	SYSTEMS AND METHODS OF PLATING VIA INTERCONNECTS	FARNWORTH, WARREN M.
<u>11083057</u>	Not Issued	020	03/16/2005	APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER	FARNWORTH, WARREN M.
<u>11052378</u>	Not Issued	020	02/07/2005	SEMICONDUCTOR COMPONENT AND SYSTEM HAVING THINNED, ENCAPSULATED DICE	FARNWORTH, WARREN M.
<u>11052279</u>	Not Issued	020	02/07/2005	ENCAPSULATED SEMICONDUCTOR COMPONENT HAVING THINNED DIE WITH CONDUCTIVE VIAS	FARNWORTH, WARREN M.
<u>11052181</u>	Not Issued	030	02/07/2005	CONDUCTIVE THROUGH WAFER VIAS	FARNWORTH, WARREN M.
<u>11050100</u>	Not Issued	041	02/03/2005	MODULAR SOCKETS USING FLEXIBLE INTERCONNECTS	FARNWORTH, WARREN M.
<u>11048227</u>	Not Issued	030	02/01/2005	WAFER-LEVEL TESTING APPARATUS	FARNWORTH, WARREN M.
<u>11040555</u>	Not Issued	030	01/21/2005	SEMICONDUCTOR PACKAGE INCLUDING FLEX CIRCUIT, INTERCONNECTS AND DENSE ARRAY EXTERNAL CONTACTS	FARNWORTH, WARREN M.
<u>11031160</u>	Not Issued	030	01/06/2005	SEMICONDUCTOR INTERCONNECT HAVING CONDUCTIVE SPRING	FARNWORTH, WARREN M.

28

				CONTACTS	
<u>11030772</u>	Not Issued	030	01/06/2005	METHOD FOR FABRICATING A SEMICONDUCTOR INTERCONNECT HAVING CONDUCTIVE SPRING CONTACTS	FARNWORTH, WARREN M.
<u>11012569</u>	Not Issued	030	12/15/2004	METHODS FOR FORMING PROTECTIVE LAYERS ON SEMICONDUCTOR DEVICE SUBSTRATES	FARNWORTH, WARREN M.
<u>11009829</u>	Not Issued	041	12/10/2004	DEVICE AND METHOD FOR ISOLATING A SHORT-CIRCUITED INTEGRATED CIRCUIT (IC) FROM OTHER ICs ON A SEMICONDUCTOR WAFER	FARNWORTH, WARREN M.
<u>11008654</u>	Not Issued	030	12/09/2004	USE OF PALLADIUM IN IC MANUFACTURING WITH CONDUCTIVE POLYMER BUMP	FARNWORTH, WARREN M.
<u>11002031</u>	Not Issued	041	12/01/2004	METHOD FOR FABRICATING A SEMICONDUCTOR COMPONENT USING CONTACT PRINTING	FARNWORTH, WARREN M.
<u>10998269</u>	Not Issued	030	11/26/2004	TEST SYSTEM WITH INTERCONNECT HAVING CONDUCTIVE MEMBERS AND CONTACTS ON OPPOSING SIDES	FARNWORTH, WARREN M.
<u>10987843</u>	Not Issued	030	11/12/2004	LAYER THICKNESS CONTROL FOR STEREOLITHOGRAPHY UTILIZING VARIABLE LIQUID ELEVATION AND LASER FOCAL LENGTH	FARNWORTH, WARREN M.
<u>10932296</u>	Not Issued	030	09/02/2004	THROUGH-WAFER INTERCONNECTS FOR PHOTOIMAGER AND MEMORY WAFERS	FARNWORTH, WARREN
<u>10847969</u>	Not Issued	094	05/18/2004	METHOD AND APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DIE	FARNWORTH, WARREN
<u>10701128</u>	Not Issued	092	11/03/2003	MICROELECTRONIC DEVICE PACKAGES AND METHODS FOR CONTROLLING THE DISPOSITION OF NON-	FARNWORTH, WARREN

				CONDUCTIVE MATERIALS IN SUCH PACKAGES	
<u>10304911</u>	<u>6777261</u>	150	11/26/2002	METHOD AND APPARATUS FOR A SEMICONDUCTOR PACKAGE FOR VERTICAL SURFACE MOUNTING	FARNWORTH, WARREN
<u>10190019</u>	<u>6673649</u>	150	07/05/2002	MICROELECTRONIC DEVICE PACKAGES AND METHODS FOR CONTROLLING THE DISPOSITION OF NON-CONDUCTIVE MATERIALS IN SUCH PACKAGES	FARNWORTH, WARREN
<u>10132429</u>	<u>6828173</u>	150	04/25/2002	SEMICONDUCTOR DEVICE INCLUDING EDGE BOND PADS AND METHODS	FARNWORTH, WARREN M.
<u>10094161</u>	<u>6908784</u>	150	03/06/2002	METHOD FOR FABRICATING ENCAPSULATED SEMICONDUCTOR COMPONENTS	FARNWORTH, WARREN M.
<u>09949683</u>	<u>6903465</u>	150	09/10/2001	METHOD AND APPARATUS FOR A SEMICONDUCTOR PACKAGE FOR VERTICAL SURFACE MOUNTING	FARNWORTH, WARREN
<u>09749110</u>	<u>6511863</u>	150	12/26/2000	METHOD AND APPARATUS FOR A SEMICONDUCTOR PACKAGE FOR VERTICAL SURFACE MOUNTING	FARNWORTH, WARREN
<u>09651999</u>	<u>6477662</u>	150	08/31/2000	APPARATUS AND METHOD IMPLEMENTING REPAIRS ON A MEMORY DEVICE	FARNWORTH, WARREN M
<u>09388032</u>	<u>6082605</u>	150	09/01/1999	CONTINUOUS MODE SOLDER JET APPARATUS	FARNWORTH, WARREN M
<u>09302833</u>	<u>6204678</u>	150	04/30/1999	DIRECT CONNECT INTERCONNECT FOR TESTING SEMICONDUCTOR DICE AND WAFERS	FARNWORTH, WARREN M
<u>09275791</u>	<u>6437591</u>	150	03/25/1999	TEST INTERCONNECT FOR BUMPED SEMICONDUCTOR COMPONENTS AND METHOD OF FABRICATION	FARNWORTH, WARREN M
<u>09266237</u>	Not Issued	094	03/10/1999	TEST INTERCONNECT FOR BUMPED SEMICONDUCTOR COMPONENTS AND METHOD OF FABRICATION	FARNWORTH, WARREN M.
<u>09259142</u>	<u>6549821</u>	150	02/26/1999	STEREOLITHOGRAPHIC METHOD AND APPARATUS	FARNWORTH, WARREN M

				FOR PACKAGING ELECTRONIC COMPONENTS AND RESULTING STRUCTURES	
<u>09244733</u>	<u>6084288</u>	150	02/05/1999	HERMETIC CHIP AND METHOD OF MANUFACTURE	FARNWORTH, WARREN M
<u>09143765</u>	<u>6291894</u>	150	08/31/1998	METHOD AND APPARATUS FOR A SEMICONDUCTOR PACKAGE FOR VERTICAL SURFACE MOUNTING	FARNWORTH, WARREN
<u>08975553</u>	<u>6219908</u>	150	11/20/1997	METHOD AND APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DIE	FARNWORTH, WARREN
<u>08975549</u>	<u>6763578</u>	150	11/20/1997	METHOD AND APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DIE	FARNWORTH, WARREN
<u>08962229</u>	<u>6124721</u>	150	10/31/1997	METHOD OF TESTING THE OOPERABILITY OF INTEGRATED CIRCUITRY OF A SUBSTRATE BY ENGAGING ELECTRICALLY CONDUCTIVE TEST PADS ON THE SUBSTRATE	FARNWORTH, WARREN
<u>08838010</u>	<u>5910921</u>	150	04/22/1997	SELF-TEST OF A MEMORY DEVICE	FARNWORTH, WARREN M
<u>08823468</u>	<u>5796264</u>	150	03/19/1997	APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DICE	FARNWORTH, WARREN
<u>08821468</u>	<u>6025731</u>	150	03/21/1997	HYBRID INTERCONNECT AND SYSTEM FOR TESTING SEMICONDUCTOR DICE	FARNWORTH, WARREN M
<u>08758657</u>	Not Issued	161	12/02/1996	METHOD AND APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DIE	FARNWORTH, WARREN
<u>08692883</u>	<u>5958100</u>	150	07/31/1996	PROCESS OF MAKING A GLASS SEMICONDUCTOR PACKAGE	FARNWORTH, WARREN
<u>08691759</u>	<u>6005290</u>	150	08/02/1996	MULTI CHIP MODULE HAVING SELF LIMITING CONTACT MEMBERS	FARNWORTH, WARREN
<u>08621157</u>	Not	161	03/21/1996	METHOD AND APPARATUS	FARNWORTH,

	Issued			FOR TESTING SEMICONDUCTOR CIRCUITRY FOR OPERABILITY AND METHOD OF FORMING APPARATUS FOR TESTING SEMICONDUCTOR CIRCUITRY FOR OPERABILITY	WARREN
<a href="#">08485086</a>	<a href="#">5640762</a>	150	06/07/1995	METHOD AND APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DIE	FARNWORTH, WARREN
<a href="#">08452990</a>	<a href="#">5559444</a>	150	05/30/1995	METHOD AND APPARATUS FOR TESTING UNPACKAGED SEMICONDUCTOR DICE	FARNWORTH, WARREN
<a href="#">08452798</a>	<a href="#">5607818</a>	150	05/30/1995	MAKING INTERCONNECTS AND SEMICONDUCTOR STRUCTURES USING ELECTROPHORETIC PHOTORESIST DEPOSITION	FARNWORTH, WARREN
<a href="#">08431452</a>	<a href="#">5578526</a>	150	05/01/1995	METHOD FOR FORMING A MULTI CHIP MODULE (MCM)	FARNWORTH, WARREN
<a href="#">08343730</a>	<a href="#">5487999</a>	150	11/22/1994	METHOD FOR FABRICATING A PENETRATION LIMITED CONTACT HAVING A ROUGH TEXTURED SURFACE	FARNWORTH, WARREN M
<a href="#">08338345</a>	<a href="#">5634267</a>	150	11/14/1994	METHOD AND APPARATUS FOR MANUFACTURING KNOWN GOOD SEMICONDUCTOR DIE	FARNWORTH, WARREN

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Your Search was:

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First Name = WARREN

Application#	Patent#	Status	Date Filed	Title	Inventor Name 50
<a href="#">10443347</a>	<a href="#">6781848</a>	150	05/22/2003	SINGLE-PIECE MOLDED MODULE HOUSING	FARNWORTH, WARREN M.
<a href="#">10430616</a>	Not Issued	094	05/05/2003	USE OF PALLADIUM IN IC MANUFACTURING WITH CONDUCTIVE POLYMER BUMP	FARNWORTH, WARREN M.
<a href="#">10427518</a>	Not Issued	120	05/01/2003	METHODS FOR MODIFYING A VERTICAL SURFACE MOUNT PACKAGE	FARNWORTH, WARREN M.
<a href="#">10423240</a>	<a href="#">6815327</a>	150	04/25/2003	MASK REPATTERN PROCESS	FARNWORTH, WARREN M.
<a href="#">10401209</a>	Not Issued	092	03/27/2003	METHOD FOR USING DATA REGARDING MANUFACTURING PROCEDURES INTEGRATED CIRCUITS (IC'S) HAVE UNDERGONE, SUCH AS REPAIRS, TO SELECT PROCEDURES THE IC'S UNDERGO, SUCH AS ADDITIONAL REPAIRS	FARNWORTH, WARREN M.
<a href="#">10401199</a>	Not Issued	094	03/27/2003	APPARATUS FOR FORMING MODULAR SOCKETS USING FLEXIBLE INTERCONNECTS AND RESULTING STRUCTURES	FARNWORTH, WARREN M.
<a href="#">10396163</a>	<a href="#">6801048</a>	150	03/25/2003	DEVICE AND METHOD FOR TESTING INTEGRATED CIRCUIT DICE IN AN INTEGRATED CIRCUIT MODULE	FARNWORTH, WARREN M.
<a href="#">10391067</a>	<a href="#">6852999</a>	150	03/17/2003	REDUCED TERMINAL TESTING SYSTEM	FARNWORTH, WARREN M.
<a href="#">10390863</a>	<a href="#">6906418</a>	150	03/17/2003	SEMICONDUCTOR	FARNWORTH,

				COMPONENT HAVING ENCAPSULATED, BONDED, INTERCONNECT CONTACTS	WARREN M.
<u>10370755</u>	Not Issued	041	02/20/2003	CHIP SCALE PACKAGE STRUCTURES AND METHOD OF FORMING CONDUCTIVE BUMPS THEREON	FARNWORTH, WARREN M.
<u>10359778</u>	<u>6662243</u>	150	02/07/2003	MEMORY UNIT, A METHOD OF ASSEMBLING A MEMORY UNIT, A METHOD OF RECONFIGURING A SYSTEM, AND A MEMORY DEVICE	FARNWORTH, WARREN M.
<u>10357656</u>	<u>6787394</u>	150	02/03/2003	METHODS OF WAFER LEVEL FABRICATION AND ASSEMBLY OF CHIP SCALE PACKAGES	FARNWORTH, WARREN M.
<u>10357587</u>	<u>6768209</u>	150	02/03/2003	UNDERFILL COMPOUNDS INCLUDING ELECTRICALLY CHARGED FILLER ELEMENTS, MICROELECTRONIC DEVICES HAVING UNDERFILL COMPOUNDS INCLUDING ELECTRICALLY CHARGED FILLER ELEMENTS, AND METHODS OF UNDERFILLING MICROELECTRONIC DEVICES	FARNWORTH, WARREN M.
<u>10342798</u>	Not Issued	094	01/13/2003	THE USE OF NITRIDES FOR FLIP-CHIP ENCAPSULATION	FARNWORTH, WARREN M.
<u>10341451</u>	<u>6713788</u>	150	01/14/2003	OPTO-ELECTRIC MOUNTING APPARATUS	FARNWORTH, WARREN M.
<u>10193567</u>	<u>6803303</u>	150	07/11/2002	METHOD OF FABRICATING SEMICONDUCTOR COMPONENT HAVING ENCAPSULATED, BONDED, INTERCONNECT CONTACTS	FARNWORTH, WARREN M.
<u>10193001</u>	<u>6767817</u>	150	07/11/2002	ASYMMETRIC PLATING	FARNWORTH, WARREN M.
<u>10191424</u>	Not Issued	094	07/08/2002	SEMICONDUCTOR DEVICES WITH PERMANENT POLYMER STENCIL AND METHOD FOR MANUFACTURING THE SAME	FARNWORTH, WARREN M.
<u>10107884</u>	<u>6600171</u>	150	03/28/2002	SEMICONDUCTOR COMPONENT AND SYSTEM FOR FABRICATING CONTACTS ON SEMICONDUCTOR COMPONENTS	FARNWORTH, WARREN M.
<u>10099483</u>	<u>6684493</u>	150	03/13/2002	METHOD OF CONNECTING	FARNWORTH,

				SEMICONDUCTOR DEVICE TO A SUBSTRATE	WARREN M.
<u>10092829</u>	<u>6515325</u>	150	03/06/2002	NANOTUBE SEMICONDUCTOR DEVICES AND METHODS FOR MAKING THE SAME	FARNWORTH, WARREN M.
<u>10074844</u>	<u>6514798</u>	150	02/13/2002	STEREOLITHOGRAPHIC METHODS FOR FABRICATING HERMETIC SEMICONDUCTOR DEVICE PACKAGES AND SEMICONDUCTOR DEVICES INCLUDING STEREOLITHOGRAPHICALLY FABRICATED HERMETIC PACKAGES	FARNWORTH, WARREN M.
<u>10074840</u>	<u>6593171</u>	150	02/13/2002	STEREOLITHOGRAPHIC METHODS FOR FABRICATING HERMETIC SEMICONDUCTOR DEVICE PACKAGES AND SEMICONDUCTOR DEVICES INCLUDING STEREOLITHOGRAPHICALLY FABRICATED HERMETIC PACKAGES	FARNWORTH, WARREN M.
<u>10072734</u>	<u>6798224</u>	150	02/05/2002	METHOD FOR TESTING SEMICONDUCTOR WAFERS	FARNWORTH, WARREN M.
<u>10035078</u>	Not Issued	093	12/28/2001	LOC SEMICONDUCTOR ASSEMBLED WITH ROOM TEMPRATURE ADHESIVE	FARNWORTH, WARREN M.
<u>10017419</u>	<u>6555460</u>	150	12/12/2001	METHODS FOR MASK REPATTERN PROCESS	FARNWORTH, WARREN M.
<u>09921205</u>	<u>6426562</u>	150	08/02/2001	MASK REPATTERN PROCESS	FARNWORTH, WARREN M.
<u>09917130</u>	<u>6541850</u>	150	07/27/2001	UTILIZATION OF DIE ACTIVE SURFACES FOR Laterally EXTENDING DIE INTERNAL AND EXTERNAL CONNECTIONS	FARNWORTH, WARREN M.
<u>09906294</u>	<u>6469537</u>	150	07/16/2001	SYSTEM FOR TESTING SEMICONDUCTOR WAFERS HAVING INTERCONNECT WITH PRESSURE SENSING MECHANISM	FARNWORTH, WARREN M.
<u>09892156</u>	<u>6420681</u>	150	06/26/2001	METHOD AND PROCESS OF CONTACT TO A HEAT SOFTENED SOLDER BALL ARRAY	FARNWORTH, WARREN M.



<u>09885325</u>	<u>6426639</u>	150	06/19/2001	METHOD AND APPARATUS FOR CAPACITIVELY TESTING A SEMICONDUCTOR DIE	FARNWORTH, WARREN M.
<u>09875063</u>	Not Issued	061	06/06/2001	GROUP ENCAPSULATED DICING CHUCK	FARNWORTH, WARREN M.
<u>09867374</u>	<u>6395566</u>	150	05/29/2001	METHOD OF WIRE-BONDING A REPAIR DIE IN A MULTI-CHIP MODULE USING A REPAIR SOLUTION GENERATED DURING TESTING OF THE MODULE	FARNWORTH, WARREN M.
<u>09844532</u>	Not Issued	061	04/30/2001	METHOD FOR FABRICATING A TEST INTERCONNECT FOR BUMPED SEMICONDUCTOR COMPONENTS BY FORMING RECESSES AND CANTILEVERED LEADS ON A SUBSTRATE	FARNWORTH, WARREN M.
<u>09808879</u>	<u>6573740</u>	150	03/14/2001	METHOD OF FORMING AN APPARATUS CONFIGURED TO ENGAGE AN ELECTRICALLY CONDUCTIVE PAD ON A SEMICONDUCTIVE SUBSTRATE AND A METHOD OF ENGAGING ELECTRICALLY CONDUCTIVE PADS ON A SEMICONDUCTIVE SUBSTRATE	FARNWORTH, WARREN M.
<u>09797743</u>	<u>6356092</u>	150	03/02/2001	METHOD AND APPARATUS FOR CAPACITIVELY TESTING A SEMICONDUCTOR DIE	FARNWORTH, WARREN M.
<u>09754671</u>	<u>6365501</u>	150	01/04/2001	MASK REPATTERN PROCESS	FARNWORTH, WARREN M.
<u>09734383</u>	<u>6379983</u>	150	12/11/2000	METHOD OF WIRE-BONDING A REPAIR DIE IN A MULTI-CHIP MODULE USING A REPAIR SOLUTION GENERATED DURING TESTING OF THE MODULE	FARNWORTH, WARREN M.
<u>09733572</u>	<u>6509647</u>	150	12/08/2000	APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER	FARNWORTH, WARREN M.
<u>09723101</u>	<u>6396291</u>	150	11/28/2000	METHOD FOR TESTING SEMICONDUCTOR COMPONENTS	FARNWORTH, WARREN M.
<u>09660782</u>	<u>6410406</u>	150	09/13/2000	SEMICONDUCTOR DEVICE	FARNWORTH,

				INCLUDING EDGE BOND PADS AND METHODS	WARREN M.
<a href="#">09534822</a>	<a href="#">6686758</a>	150	03/23/2000	ENGAGEMENT PROBE AND APPARATUSES CONFIGURED TO ENGAGE A CONDUCTIVE PAD	FARNWORTH, WARREN M.
<a href="#">09533407</a>	<a href="#">6529027</a>	150	03/23/2000	INTERPOSER AND METHODS FOR FABRICATING SAME	FARNWORTH, WARREN M.
<a href="#">09525017</a>	<a href="#">6514787</a>	150	03/14/2000	OPTO-ELECTRIC MOUNTING APPARATUS	FARNWORTH, WARREN M.
<a href="#">09524800</a>	<a href="#">6705513</a>	150	03/14/2000	METHODS OF BONDING SOLDER BALLS TO BOND PADS ON A SUBSTRATE, AND BONDING FRAMES	FARNWORTH, WARREN M.
<a href="#">09513274</a>	Not Issued	160	02/24/2000	METHOD OF STRESS TESTING MEMORY INTEGRATED CIRCUITS	FARNWORTH, WARREN M.
<a href="#">09505214</a>	<a href="#">6228677</a>	150	02/16/2000	VERTICAL SURFACE MOUNT ASSEMBLY AND METHODS	FARNWORTH, WARREN M.
<a href="#">09499768</a>	<a href="#">6362642</a>	150	02/08/2000	METHOD OF CHIP TESTING OF CHIP LEADS CONSTRAINED IN DIELECTRIC MEDIA	FARNWORTH, WARREN M.
<a href="#">09482416</a>	<a href="#">6453550</a>	150	01/13/2000	METHOD AND APPARATUS FOR FORMING MODULAR SOCKETS USING FLEXIBLE INTERCONNECTS AND RESULTING STRUCTURES	FARNWORTH, WARREN M.
<a href="#">09479894</a>	<a href="#">6407570</a>	150	01/18/2000	INTERCONNECT FOR TESTING SEMICONDUCTOR COMPONENT FLEXURE	FARNWORTH, WARREN M.

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Application#	Patent#	Status	Date Filed	Title	Inventor Name 50
<a href="#">09819297</a>	<a href="#">6455351</a>	150	03/27/2001	VERTICAL SURFACE MOUNT ASSEMBLY AND METHODS	FARNWORTH, WARREN M.
<a href="#">09797795</a>	<a href="#">6369597</a>	150	03/02/2001	METHOD AND APPARATUS FOR CAPACITIVELY TESTING A SEMICONDUCTOR DIE	FARNWORTH, WARREN M.
<a href="#">09797368</a>	<a href="#">6605956</a>	150	03/01/2001	DEVICE AND METHOD FOR TESTING INTEGRATED CIRCUIT DICE IN AN INTEGRATED CIRCUIT MODULE	FARNWORTH, WARREN M.
<a href="#">09795889</a>	<a href="#">6391680</a>	150	02/28/2001	LOC SEMICONDUCTOR ASSEMBLED WITH ROOM TEMPERATURE ADHESIVE	FARNWORTH, WARREN M.
<a href="#">09769983</a>	<a href="#">6407451</a>	150	01/25/2001	MICROMACHINED CHIP SCALE PACKAGE	FARNWORTH, WARREN M.
<a href="#">09749173</a>	<a href="#">6400174</a>	150	12/27/2000	TEST SYSTEM HAVING ALIGNMENT MEMBER FOR ALIGNING SEMICONDUCTOR COMPONENTS	FARNWORTH, WARREN M.
<a href="#">09745093</a>	<a href="#">6353328</a>	150	12/20/2000	TEST SYSTEM WITH MECHANICAL ALIGNMENT FOR SEMICONDUCTOR CHIP SCALE PACKAGES AND DICE	FARNWORTH, WARREN M.
<a href="#">09738915</a>	<a href="#">6437451</a>	150	12/14/2000	TEST INTERCONNECT FOR SEMICONDUCTOR COMPONENTS HAVING BUMPED AND PLANAR CONTACTS	FARNWORTH, WARREN M.
<a href="#">09737288</a>	<a href="#">6570771</a>	150	12/13/2000	SINGLE-PIECE MOLDED MODULE HOUSING	FARNWORTH, WARREN M.
<a href="#">09734514</a>	<a href="#">6297660</a>	150	12/12/2000	TEST CARRIER WITH VARIABLE FORCE APPLYING MECHANISM FOR TESTING SEMICONDUCTOR	FARNWORTH, WARREN M.

				COMPONENTS	
<u>09732106</u>	<u>6442044</u>	150	12/07/2000	SEMICONDUCTOR DEVICE SOCKET, ASSEMBLY AND METHODS	FARNWORTH, WARREN M.
<u>09693443</u>	<u>6319354</u>	150	10/20/2000	SYSTEM AND METHOD FOR DICING SEMICONDUCTOR COMPONENTS	FARNWORTH, WARREN M.
<u>09685132</u>	<u>6420892</u>	150	10/10/2000	CALIBRATION TARGET FOR CALIBRATING SEMICONDUCTOR WAFER TEST SYSTEMS	FARNWORTH, WARREN M.
<u>09677555</u>	<u>6544461</u>	150	10/02/2000	TEST CARRIER WITH MOLDED INTERCONNECT FOR TESTING SEMICONDUCTOR COMPONENTS	FARNWORTH, WARREN M.
<u>09653366</u>	<u>6756253</u>	150	09/01/2000	METHOD FOR FABRICATING A SEMICONDUCTOR COMPONENT WITH EXTERNAL CONTACT POLYMER SUPPORT LAYER	FARNWORTH, WARREN M.
<u>09653272</u>	Not Issued	061	08/31/2000	METHOD FOR USING DATA REGARDING MANUFACTURING PROCEDURES INTEGRATED CIRCUITS (IC'S) HAVE UNDERGONE, SUCH AS REPAIRS, TO SELECT PROCEDURES THE IC'S WILL UNDERGO, SUCH AS ADDITIONAL REPAIRS	FARNWORTH, WARREN M.
<u>09652923</u>	<u>6757972</u>	150	08/31/2000	ELECTRICAL CONNECTOR	FARNWORTH, WARREN M.
<u>09652922</u>	<u>6397460</u>	150	08/31/2000	ELECTRICAL CONNECTOR	FARNWORTH, WARREN M.
<u>09652724</u>	<u>6729027</u>	150	08/31/2000	METHOD OF FORMING RECESSED SOCKET CONTACTS	FARNWORTH, WARREN M.
<u>09652720</u>	<u>6648654</u>	150	08/31/2000	ELECTRICAL CONNECTOR	FARNWORTH, WARREN M.
<u>09652585</u>	Not Issued	093	08/31/2000	PROCESS OF FORMING SOCKET CONTACTS	FARNWORTH, WARREN M.
<u>09652340</u>	<u>6544902</u>	150	08/31/2000	ENERGY BEAM PATTERNING OF PROTECTIVE LAYERS FOR SEMICONDUCTOR DEVICES	FARNWORTH, WARREN M.
<u>09652060</u>	<u>6656754</u>	150	08/31/2000	METHOD OF FORMING A SEMICONDUCTOR CHIP	FARNWORTH, WARREN M.

				CARRIER	
<u>09651863</u>	<u>6562278</u>	150	08/29/2000	STEREOLITHOGRAPHIC FABRICATION OF MONOLITHIC HOUSING STRUCTURES FOR MACHINES	FARNWORTH, WARREN M.
<u>09651860</u>	<u>6628128</u>	150	08/30/2000	CSP BGA TEST SOCKET WITH INSERT AND METHOD	FARNWORTH, WARREN M.
<u>09651601</u>	<u>6358833</u>	150	08/30/2000	METHOD OF FABRICATING A MICROMACHINED CHIP SCALE PACKAGE	FARNWORTH, WARREN M.
<u>09651491</u>	<u>6437435</u>	150	08/30/2000	VERTICALLY MOUNTABLE INTERPOSER, ASSEMBLY AND METHOD	FARNWORTH, WARREN M.
<u>09651490</u>	<u>6492187</u>	150	08/30/2000	METHOD AND APPARATUS FOR AUTOMATICALLY POSITIONING ELECTRONIC DICE WITHIN COMPONENT PACKAGES	FARNWORTH, WARREN M.
<u>09651460</u>	<u>6295209</u>	150	08/30/2000	SEMICONDUCTOR DEVICE INCLUDING COMBED BOND PAD OPENING, ASSEMBLIES AND METHODS	FARNWORTH, WARREN M.
<u>09651175</u>	<u>6607689</u>	150	08/29/2000	LAYER THICKNESS CONTROL FOR STEREOLITHOGRAPHY UTILIZING VARIABLE LIQUID ELEVATION AND LASER FOCAL LENGTH	FARNWORTH, WARREN M.
<u>09651040</u>	<u>6632343</u>	150	08/30/2000	METHOD AND APPARATUS FOR ELECTROLYTIC PLATING OF SUREFACE METALS	FARNWORTH, WARREN M.
<u>09645947</u>	<u>6413862</u>	150	08/25/2000	USE OF PALLADIUM IN IC MANUFACTURING	FARNWORTH, WARREN M.
<u>09644248</u>	<u>6614249</u>	150	08/22/2000	METHOD AND APPARATUS FOR TESTING SEMICONDUCTOR CIRCUITRY FOR OPERABILITY AND METHOD OF FORMING APPARATUS FOR TESTING SEMICONDUCTOR CIRCUITRY FOR OPERABILITY	FARNWORTH, WARREN M.
<u>09642133</u>	<u>6544465</u>	150	08/18/2000	METHOD FOR FORMING THREE DIMENSIONAL STRUCTURES FROM LIQUID WITH IMPROVED SURFACE FINISH	FARNWORTH, WARREN M.
<u>09640801</u>	<u>6432752</u>	150	08/17/2000	STEREOLITHOGRAPHIC METHODS FOR FABRICATING	FARNWORTH, WARREN M.

				HERMETIC SEMICONDUCTOR DEVICE PACKAGES AND SEMICONDUCTOR DEVICES INCLUDING STEREOLITHOGRAPHICALLY FABRICATED HERMETIC PACKAGES	
<u>09639422</u>	<u>6597066</u>	150	08/14/2000	HERMETIC CHIP AND METHOD OF MANUFACTURE	FARNWORTH, WARREN M.
<u>09638276</u>	<u>6534785</u>	150	08/14/2000	REDUCED TERMINAL TESTING SYSTEM	FARNWORTH, WARREN M.
<u>09634239</u>	<u>6482576</u>	150	08/08/2000	SURFACE SMOOTHING OF STEREOLITHOGRAPHICALLY FORMED 3-D OBJECTS	FARNWORTH, WARREN M.
<u>09633915</u>	<u>6537482</u>	150	08/08/2000	UNDERFILL AND ENCAPSULATION OF CARRIER SUBSTRATE-MOUNTED FLIP- CHIP COMPONENTS USING STEREOLITHOGRAPHY	FARNWORTH, WARREN M.
<u>09631903</u>	<u>6562637</u>	150	08/04/2000	APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER	FARNWORTH, WARREN M.
<u>09631900</u>	<u>6791185</u>	150	08/04/2000	APPARATUS AND METHODS OF TESTING AND ASSEMBLING BUMPED DEVICES USING AN ANISOTROPICALLY CONDUCTIVE LAYER	FARNWORTH, WARREN M.
<u>09618885</u>	<u>6329637</u>	150	07/18/2000	METHOD AND PROCESS OF CONTACT TO A HEAT SOFTENED SOLDER BALL ARRAY	FARNWORTH, WARREN M.
<u>09606428</u>	<u>6576494</u>	150	06/28/2000	RECESSED ENCAPSULATED MICROELECTRONIC DEVICES AND METHODS FOR FORMATION	FARNWORTH, WARREN M.
<u>09596272</u>	<u>6600334</u>	150	06/16/2000	FORCE APPLYING PROBE CARD AND TEST SYSTEM FOR SEMICONDUCTOR WAFERS	FARNWORTH, WARREN M.
<u>09589841</u>	<u>6875640</u>	150	06/08/2000	STEREOLITHOGRAPHIC METHODS FOR FORMING A PROTECTIVE LAYER ON A SEMICONDUCTOR DEVICE SUBSTRATE AND SUBSTRATES INCLUDING PROTECTIVE LAYERS SO FORMED	FARNWORTH, WARREN M.

<a href="#">09580814</a>	<a href="#">6265245</a>	150	05/26/2000	COMPLIANT INTERCONNECT FOR TESTING A SEMICONDUCTOR DIE	FARNWORTH, WARREN M.
<a href="#">09536827</a>	<a href="#">6465877</a>	150	03/27/2000	SEMICONDUCTOR PACKAGE INCLUDING FLEX CIRCUIT, INTERCONNECTS AND DENSE ARRAY EXTERNAL CONTACTS	FARNWORTH, WARREN M.
<a href="#">09518293</a>	<a href="#">6287942</a>	150	03/03/2000	HERMETIC CHIP AND METHOD OF MANUFACTURE	FARNWORTH, WARREN M.
<a href="#">09505493</a>	<a href="#">6215183</a>	150	02/16/2000	VERTICAL SURFACE MOUNT ASSEMBLY AND METHODS	FARNWORTH, WARREN M.
<a href="#">09487935</a>	<a href="#">6319065</a>	150	01/20/2000	METHOD AND APPARATUS FOR FORMING MODULAR SOCKETS USING FLEXIBLE INTERCONNECTS AND RESULTING STRUCTURES	FARNWORTH, WARREN M.

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**Inventor Name Search Result**

Your Search was:

Last Name = KIRBY

First Name = KYLE

Application#	Patent#	Status	Date Filed	Title	Inventor Name 50
<u>60606798</u>	Not Issued	020	09/01/2004	METHODS AND APPARATUS FOR PLACING SUBSTRATES IN CONTACT WITH MOLTEN SOLDER	KIRBY, KYLE K.
<u>60606355</u>	Not Issued	020	08/31/2004	THROUGH-SUBSTRATE INTERCONNECT FABRICATION METHODS AND RESULTING STRUCTURES AND ASSEMBLIES	KIRBY, KYLE K.
<u>60604234</u>	Not Issued	020	08/24/2004	METHOD OF FORMING VIAS IN SEMICONDUCTOR SUBSTRATES WITHOUT DAMAGING ACTIVE REGIONS THEREOF AND RESULTING STRUCTURES	KIRBY, KYLE K.
<u>11145500</u>	Not Issued	020	06/06/2005	SEMICONDUCTOR INTERCONNECT HAVING SEMICONDUCTOR SPRING CONTACTS, TEST SYSTEMS INCORPORATING THE INTERCONNECT AND TEST METHODS USING THE INTERCONNECT	KIRBY, KYLE K.
<u>11140420</u>	Not Issued	020	05/27/2005	METHODS AND APPARATUS FOR PLACING SUBSTRATES IN CONTACT WITH MOLTEN SOLDER	KIRBY, KYLE K.
<u>11140402</u>	Not Issued	020	05/27/2005	METHOD OF FORMING VIAS IN SEMICONDUCTOR SUBSTRATES WITHOUT DAMAGING ACTIVE REGIONS THEREOF AND RESULTING STRUCTURES	KIRBY, KYLE K.
<u>11121276</u>	Not Issued	020	05/03/2005	COMPLIANT CONTACT STRUCTURES, CONTACTOR	KIRBY, KYLE K.



				CARDS AND TEST SYSTEM INCLUDING SAME, AND METHODS OF FABRICATION AND USE	
<u>11099066</u>	Not Issued	020	04/05/2005	SYSTEMS AND METHODS OF PLATING VIA INTERCONNECTS	KIRBY, KYLE K.
<u>11056211</u>	Not Issued	030	02/10/2005	MICROELECTRONIC WORKPIECES AND METHODS FOR FORMING INTERCONNECTS IN MICROELECTRONIC WORKPIECES	KIRBY, KYLE K.
<u>11044941</u>	Not Issued	071	01/27/2005	SEMICONDUCTOR INTERCONNECT HAVING SEMICONDUCTOR SPRING CONTACTS	KIRBY, KYLE K.
<u>11044443</u>	Not Issued	030	01/26/2005	VIAS HAVING VARYING DIAMETERS AND FILLS FOR USE WITH A SEMICONDUCTOR DEVICE AND METHODS OF FORMING SEMICONDUCTOR DEVICE STRUCTURES INCLUDING SAME	KIRBY, KYLE K.
<u>11031160</u>	Not Issued	030	01/06/2005	SEMICONDUCTOR INTERCONNECT HAVING CONDUCTIVE SPRING CONTACTS	KIRBY, KYLE K.
<u>11030772</u>	Not Issued	030	01/06/2005	METHOD FOR FABRICATING A SEMICONDUCTOR INTERCONNECT HAVING CONDUCTIVE SPRING CONTACTS	KIRBY, KYLE K.
<u>11028918</u>	Not Issued	020	01/03/2005	METHODS OF FABRICATING INTERCONNECTS FOR SEMICONDUCTOR COMPONENTS	KIRBY, KYLE K.
<u>11028892</u>	Not Issued	030	01/03/2005	METHODS OF FABRICATING INTERCONNECTS FOR SEMICONDUCTOR COMPONENTS	KIRBY, KYLE K.
<u>11027443</u>	Not Issued	030	12/30/2004	METHODS FOR FORMING INTERCONNECTS IN MICROELECTRONIC WORKPIECES AND MICROELECTRONIC	KIRBY, KYLE K.

				WORKPIECES FORMED USING SUCH METHODS	
<u>10999344</u>	Not Issued	071	11/30/2004	METHODS OF FORMING VIA PLUGS USING AN AEROSOL STREAM OF PARTICLES TO DEPOSIT CONDUCTIVE MATERIAL	KIRBY, KYLE K.
<u>10962931</u>	Not Issued	030	10/11/2004	MULTI-DICE CHIP SCALE SEMICONDUCTOR COMPONENTS	KIRBY, KYLE K.
<u>10932296</u>	Not Issued	030	09/02/2004	THROUGH-WAFER INTERCONNECTS FOR PHOTOIMAGER AND MEMORY WAFERS	KIRBY, KYLE
<u>10931959</u>	Not Issued	030	08/31/2004	METHODS OF MANUFACTURE OF A VIA STRUCTURE COMPRISING A PLURALITY OF CONDUCTIVE ELEMENTS, SEMICONDUCTOR DIE, MULTICHIP MODULE, AND SYSTEM INCLUDING SAME	KIRBY, KYLE K.
<u>10931847</u>	Not Issued	030	08/31/2004	WAFER REINFORCEMENT STRUCTURE AND METHODS OF FABRICATION	KIRBY, KYLE K.
<u>10928598</u>	Not Issued	030	08/27/2004	METHODS FOR FORMING VIAS OF VARYING LATERAL DIMENSIONS AND SEMICONDUCTOR COMPONENTS AND ASSEMBLIES INCLUDING SAME	KIRBY, KYLE K.
<u>10927486</u>	Not Issued	030	08/26/2004	MICROFEATURE DIES WITH POROUS REGIONS, AND ASSOCIATED METHODS AND SYSTEMS	KIRBY, KYLE K.
<u>10925501</u>	Not Issued	020	08/24/2004	METHODS FOR FORMING INTERCONNECTS IN VIAS AND MICROELECTRONIC WORKPIECES INCLUDING SUCH INTERCONNECTS	KIRBY, KYLE K.
<u>10925406</u>	Not Issued	030	08/24/2004	MICROELECTRONIC IMAGERS WITH OPTICAL DEVICES HAVING INTEGRAL REFERENCE FEATURES AND METHODS FOR MANUFACTURING SUCH MICROELECTRONIC IMAGERS	KIRBY, KYLE K.

<u>10919604</u>	Not Issued	030	08/16/2004	FRAME STRUCTURE AND SEMICONDUCTOR ATTACH PROCESS FOR USE THEREWITH FOR FABRICATION OF IMAGE SENSOR PACKAGES AND THE LIKE, AND RESULTING PACKAGES	KIRBY, KYLE K.
<u>10894262</u>	Not Issued	030	07/19/2004	MICROELECTRONIC IMAGERS WITH OPTICAL DEVICES AND METHODS OF MANUFACTURING SUCH MICROELECTRONIC IMAGERS	KIRBY, KYLE K.
<u>10879838</u>	Not Issued	030	06/29/2004	MICROELECTRONIC DEVICES AND METHODS FOR FORMING INTERCONNECTS IN MICROELECTRONIC DEVICES	KIRBY, KYLE K.
<u>10879398</u>	Not Issued	030	06/29/2004	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	KIRBY, KYLE K.
<u>10871153</u>	Not Issued	030	06/18/2004	COMPLIANT SPRING CONTACTS, METHODS OF MAKING, AND UTILIZATION AS ELECTRICAL CONTACTS IN PROBE CARD AND FLIP-CHIP APPLICATIONS	KIRBY, KYLE K.
<u>10867352</u>	Not Issued	071	06/14/2004	MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	KIRBY, KYLE K.
<u>10864974</u>	Not Issued	030	06/10/2004	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	KIRBY, KYLE K.
<u>10860699</u>	Not Issued	030	06/02/2004	SYSTEMS AND METHODS FOR TESTING MICROELECTRONIC IMAGERS AND MICROFEATURE DEVICES	KIRBY, KYLE K.
<u>10804366</u>	Not	030	03/19/2004	ETCH SOLUTION FOR	KIRBY, KYLE K.

	Issued			SELECTIVELY REMOVING SILICON AND METHODS OF SELECTIVELY REMOVING SILICON	
<u>10791195</u>	Not Issued	041	03/02/2004	COMPLIANT CONTACT PIN ASSEMBLY, CARD SYSTEM AND METHODS THEREOF	KIRBY, KYLE K.
<u>10785466</u>	Not Issued	030	02/23/2004	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	KIRBY, KYLE K.
<u>10784074</u>	Not Issued	094	02/20/2004	METHODS OF FABRICATING INTERCONNECTS FOR SEMICONDUCTOR COMPONENTS	KIRBY, KYLE K.
<u>10733226</u>	Not Issued	020	12/10/2003	MICROELECTRONIC DEVICES AND METHODS FOR FILLING VIAS IN MICROELECTRONIC DEVICES	KIRBY, KYLE K.
<u>10730333</u>	Not Issued	030	12/08/2003	WAFER LEVEL METHODS FOR FABRICATING MULTI-DICE CHIP SCALE SEMICONDUCTOR COMPONENTS	KIRBY, KYLE K.
<u>10713878</u>	Not Issued	071	11/13/2003	MICROELECTRONIC DEVICES, METHODS FOR FORMING VIAS IN MICROELECTRONIC DEVICES, AND METHODS FOR PACKAGING MICROELECTRONIC DEVICES	KIRBY, KYLE K.
<u>10690417</u>	Not Issued	030	10/20/2003	METHODS OF COATING AND SINGULATING WAFERS AND CHIP-SCALE PACKAGES FORMED THEREFROM	KIRBY, KYLE K.
<u>10684621</u>	Not Issued	041	10/14/2003	COMPLIANT CONTACT STRUCTURES, CONTACTOR CARDS AND TEST SYSTEM INCLUDING SAME, AND METHODS OF FABRICATION AND USE	KIRBY, KYLE K.
<u>10682703</u>	Not Issued	094	10/09/2003	METHODS OF PLATING VIA INTERCONNECTS	KIRBY, KYLE K.
<u>10673692</u>	Not Issued	041	09/29/2003	METHOD FOR CREATING ELECTRICAL PATHWAYS FOR	KIRBY, KYLE K.

				SEMICONDUCTOR DEVICE STRUCTURES USING LASER MACHINING PROCESSES	
<u>10666742</u>	Not Issued	041	09/19/2003	METHODS FOR THINNING SEMICONDUCTOR SUBSTRATES THAT EMPLOY SUPPORT STRUCTURES FORMED ON THE SUBTRATES	KIRBY, KYLE K.
<u>10619650</u>	Not Issued	041	07/14/2003	SEMICONDUCTOR INTERCONNECT HAVIN COMPLIANT CONDUCTIVE CONTACTS	KIRBY, KYLE K.
<u>10379949</u>	Not Issued	071	03/06/2003	TEST SYSTEM AND TEST METHOD WITH INTERCONNECT HAVING SEMICONDUCTOR SPRING CONTACTS	KIRBY, KYLE K.
<u>10370363</u>	<u>6819512</u>	150	02/18/2003	TRIPLE-ATTRIBUTE METHOD OF ENCODING AND DECODING MAGNETIC DATA	KIRBY, KYLE K.
<u>10161290</u>	<u>6641175</u>	150	06/03/2002	RAMP-LOCK FITTING DEVICE	KIRBY, KYLE K.

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## Inventor Name Search Result

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Last Name = KIRBY

First Name = KYLE

Application#	Patent#	Status	Date Filed	Title	Inventor Name 8
<a href="#">10919821</a>	<a href="#">6922297</a>	150	08/17/2004	DOUBLE-ATTRIBUTE METHOD OF ENCODING AND DECODING MAGNETIC DATA	KIRBY, KYLE KENDRICK
<a href="#">10653766</a>	Not Issued	095	09/03/2003	PROBE CARD FOR USE WITH MICROELECTRONIC COMPONENTS, AND METHODS FOR MAKING SAME	KIRBY, KYLE K.
<a href="#">10613235</a>	<a href="#">6855631</a>	150	07/03/2003	METHODS OF FORMING VIA PLUGS USING AN AEROSOL STREAM OF PARTICLES TO DEPOSIT CONDUCTIVE MATERIAL	KIRBY, KYLE K.
<a href="#">10403937</a>	<a href="#">6841883</a>	150	03/31/2003	MULTI-DICE CHIP SCALE SEMICONDUCTOR COMPONENTS AND WAFER LEVEL METHODS OF FABRICATION	KIRBY, KYLE K.
<a href="#">09724469</a>	<a href="#">6422607</a>	150	11/28/2000	RAMP-LOCK FITTING DEVICE	KIRBY, KYLE K.
<a href="#">09630922</a>	<a href="#">6299215</a>	150	08/02/2000	COUPLING FITTING	KIRBY, KYLE K.
<a href="#">09088401</a>	<a href="#">6250688</a>	150	06/01/1998	RAMP-LOCK LIFTING DEVICE	KIRBY, KYLE K.

Inventor Search Completed: No Records to Display.

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## Inventor Name Search Result

Your Search was:

Last Name = HIATT

First Name = WILLIAM

Application#	Patent#	Status	Date Filed	Title	Inventor Name 50
<u>11146783</u>	Not Issued	020	06/07/2005	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	HIATT, WILLIAM M.
<u>11133085</u>	Not Issued	020	05/19/2005	BACKSIDE METHOD AND SYSTEM FOR FABRICATING SEMICONDUCTOR COMPONENTS WITH CONDUCTIVE INTERCONNECTS	HIATT, WILLIAM M.
<u>10981023</u>	Not Issued	040	11/04/2004	FOLDABLE BED WITH FOLDABLE GUARDRAIL	HIATT, WILLIAM CHARLES
<u>10980554</u>	Not Issued	020	11/03/2004	SYSTEM HAVING SEMICONDUCTOR COMPONENT WITH ENCAPSULATED, BONDED, INTERCONNECT CONTACTS	HIATT, WILLIAM M.
<u>10962931</u>	Not Issued	030	10/11/2004	MULTI-DICE CHIP SCALE SEMICONDUCTOR COMPONENTS	HIATT, WILLIAM M.
<u>10934635</u>	Not Issued	030	09/02/2004	SELECTIVE NICKEL PLATING OF ALUMINUM, COPPER, AND TUNGSTEN STRUCTURES	HIATT, WILLIAM M.
<u>10931678</u>	Not Issued	030	08/31/2004	METHODS FOR FABRICATION OF THIN SEMICONDUCTOR ASSEMBLIES INCLUDING REDISTRIBUTION LAYERS AND PACKAGES AND ASSEMBLIES FORMED THEREBY	HIATT, WILLIAM M.
<u>10925796</u>	Not Issued	030	08/24/2004	PASS THROUGH VIA TECHNOLOGY FOR USE DURING THE MANUFACTURE	HIATT, WILLIAM M.

				OF A SEMICONDUCTOR DEVICE	
<u>10925501</u>	Not Issued	020	08/24/2004	METHODS FOR FORMING INTERCONNECTS IN VIAS AND MICROELECTRONIC WORKPIECES INCLUDING SUCH INTERCONNECTS	HIATT, WILLIAM M.
<u>10879838</u>	Not Issued	030	06/29/2004	MICROELECTRONIC DEVICES AND METHODS FOR FORMING INTERCONNECTS IN MICROELECTRONIC DEVICES	HIATT, WILLIAM M.
<u>10879398</u>	Not Issued	030	06/29/2004	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	HIATT, WILLIAM M.
<u>10867505</u>	Not Issued	030	06/14/2004	PREFABRICATED HOUSINGS FOR MICROELECTRONIC IMAGERS AND METHODS FOR PACKAGING MICROELECTRONIC IMAGERS	HIATT, WILLIAM M.
<u>10867352</u>	Not Issued	071	06/14/2004	MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	HIATT, WILLIAM M.
<u>10864974</u>	Not Issued	030	06/10/2004	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC IMAGERS	HIATT, WILLIAM M.
<u>10863994</u>	Not Issued	030	06/09/2004	WAFER-LEVEL PACKAGED MICROELECTRONIC IMAGERS AND PROCESSES FOR WAFER-LEVEL PACKAGING	HIATT, WILLIAM M.
<u>10860699</u>	Not Issued	030	06/02/2004	SYSTEMS AND METHODS FOR TESTING MICROELECTRONIC IMAGERS AND MICROFEATURE DEVICES	HIATT, WILLIAM M.
<u>10839457</u>	Not Issued	030	05/05/2004	SYSTEMS AND METHODS FOR FORMING APERTURES IN	HIATT, WILLIAM M.



				MICROFEATURE WORKPIECES	
<u>10801205</u>	Not Issued	030	03/16/2004	STRESS AND FORCE MANAGEMENT TECHNIQUES FOR A SEMICONDUCTOR DIE	HIATT, WILLIAM M.
<u>10791195</u>	Not Issued	041	03/02/2004	COMPLIANT CONTACT PIN ASSEMBLY, CARD SYSTEM AND METHODS THEREOF	HIATT, WILLIAM M.
<u>10788941</u>	Not Issued	041	02/27/2004	ELECTRICAL CONTACTS, DEVICES INCLUDING THE SAME, AND ASSOCIATED METHODS OF FABRICATION	HIATT, WILLIAM M.
<u>10784436</u>	Not Issued	030	02/23/2004	THROUGH-HOLE CONDUCTORS FOR SEMICONDUCTOR SUBSTRATES AND METHOD AND SYSTEM FOR MAKING SAME	HIATT, WILLIAM M.
<u>10767232</u>	Not Issued	030	01/28/2004	MICROELECTRONIC DEVICES WITH IMPROVED HEAT DISSIPATION AND METHODS FOR COOLING MICROELECTRONIC DEVICES	HIATT, WILLIAM M.
<u>10762433</u>	Not Issued	092	01/22/2004	SYSTEM AND METHOD FOR THE TREATMENT OF SOOT- LADEN WATER	HIATT, WILLIAM C.
<u>10755905</u>	Not Issued	030	01/12/2004	METHODS OF FABRICATING SUBSTRATES AND SUBSTRATE PRECURSOR STRUCTURES RESULTING THEREFROM	HIATT, WILLIAM M.
<u>10733226</u>	Not Issued	020	12/10/2003	MICROELECTRONIC DEVICES AND METHODS FOR FILLING VIAS IN MICROELECTRONIC DEVICES	HIATT, WILLIAM M.
<u>10730333</u>	Not Issued	030	12/08/2003	WAFER LEVEL METHODS FOR FABRICATING MULTI- DICE CHIP SCALE SEMICONDUCTOR COMPONENTS	HIATT, WILLIAM M.
<u>10723363</u>	Not Issued	030	11/26/2003	PACKAGED MICROELECTRONIC IMAGERS AND METHODS OF PACKAGING MICROELECTRONIC	HIATT, WILLIAM M.

				IMAGERS	
<u>10713626</u>	Not Issued	030	11/13/2003	MICROELECTRONIC DEVICES HAVING CONDUCTIVE COMPLEMENTARY STRUCTURES AND METHODS OF MANUFACTURING MICROELECTRONIC DEVICES HAVING CONDUCTIVE COMPLEMENTARY STRUCTURES	HIATT, WILLIAM M.
<u>10705729</u>	Not Issued	030	11/10/2003	METHODS FOR REMOVING AND RECLAIMING UNCONSOLIDATED MATERIAL FROM SUBSTRATES FOLLOWING FABRICATION OF OBJECTS THEREON BY PROGRAMMED MATERIAL CONSOLIDATION TECHNIQUES	HIATT, WILLIAM M.
<u>10705728</u>	Not Issued	071	11/10/2003	METHODS FOR SUPPORTING SUBSTRATES DURING FABRICATION OF ONE OR MORE OBJECTS THEREON BY PROGRAMMABLE MATERIAL CONSOLIDATION TECHNIQUES	HIATT, WILLIAM M.
<u>10705409</u>	Not Issued	030	11/10/2003	SUBSTRATE SUPPORTS FOR USE WITH PROGRAMMABLE MATERIAL CONSOLIDATION APPARATUS AND SYSTEMS	HIATT, WILLIAM M.
<u>10705405</u>	Not Issued	020	11/10/2003	CLEANING COMPONENTS FOR USE WITH PROGRAMMABLE MATERIAL CONSOLIDATION APPARATUS AND SYSTEMS	HIATT, WILLIAM M.
<u>10705250</u>	Not Issued	061	11/10/2003	HANDLING SYSTEM FOR USE WITH PROGRAMMABLE MATERIAL CONSOLIDATION SYSTEMS AND ASSOCIATED METHODS	HIATT, WILLIAM M.
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